

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number: [0780790011](#)
Status: **Active**
Description: 1.00mm (.039") Pitch DDR3 DIMM Socket, Vertical, Through Hole, with Beveled Metal Pins, Black Housing and Latches, 0.76µm (30µ") Gold (Au) Plating, 2.67mm(.105") Soldertail, 240 Circuits, Lead free

Documents:

[3D Model](#) [Product Specification PS-78079-002 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

CSA LR19980
 UL E29179

General

Product Family Memory Module Sockets
 Series [78079](#)
 Component Type Socket
 JEDEC Outline MO-269
 Product Name DDR3 DIMM

Physical

Circuits (Loaded) 240
 Circuits (maximum) 240
 Color - Resin Black
 Durability (mating cycles max) 25
 Entry Angle Vertical
 Flammability 94V-0
 Function Key None
 Keying to Mating Part Yes
 Material - Metal Copper Alloy
 Material - Plating Mating Gold
 Material - Plating Termination Tin
 Material - Resin High Temperature Thermoplastic
 PC Tail Length (in) 0.105 In
 PC Tail Length (mm) 2.67 mm
 PCB Locator Yes
 PCB Retention Yes
 PCB Thickness Recommended (in) 0.062 In
 PCB Thickness Recommended (mm) 1.57 mm
 Packaging Type Tray
 Pitch - Mating Interface (in) 0.039 In
 Pitch - Mating Interface (mm) 1.00 mm
 Pitch - Term. Interface (in) 0.039 In
 Pitch - Term. Interface (mm) 1.00 mm
 Plating min: Mating (µin) 30
 Plating min: Mating (µm) 0.76
 Plating min: Termination (µin) 100
 Plating min: Termination (µm) 2.54
 Temperature Range - Operating -55°C to +85°C
 Termination Interface: Style Through Hole

Electrical

Current - Maximum per Contact 1A
 Voltage - Maximum 30V AC (RMS)/DC
 Voltage Key Center

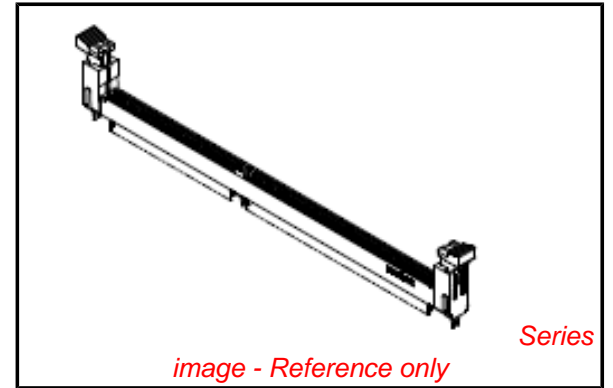


image - Reference only

EU RoHS

ELV and RoHS Compliant
REACH SVHC
 Not Reviewed
Halogen-Free Status
Not Reviewed

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

[78079Series](#)

Mates With

JEDEC standard 1.27mm modules

Solder Process Data

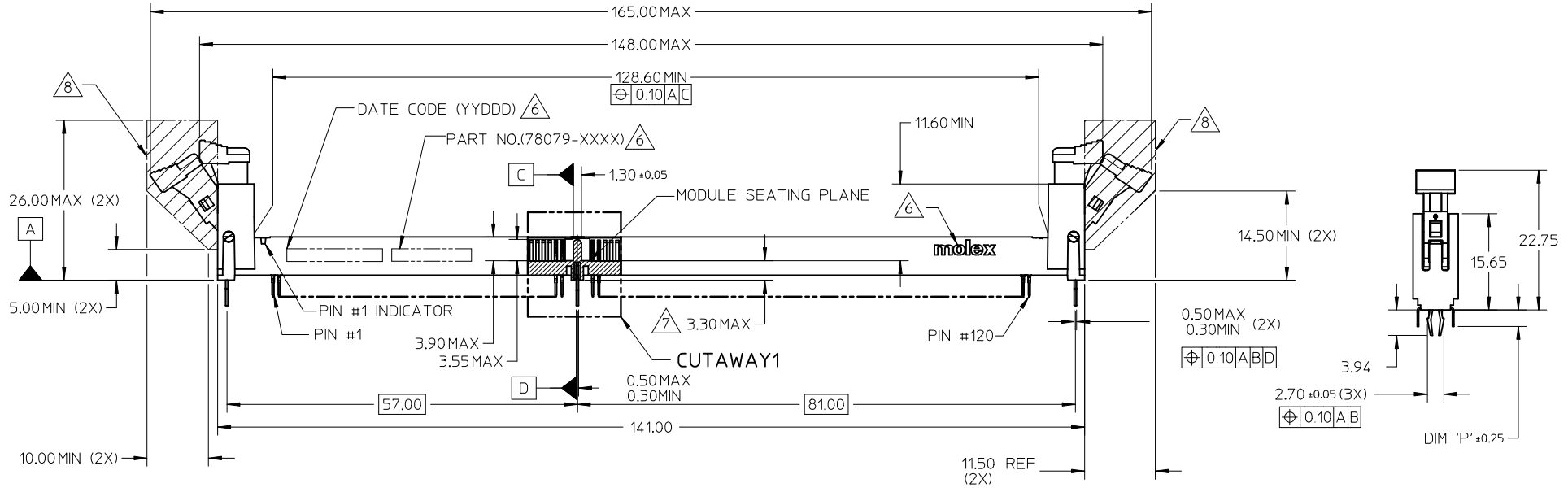
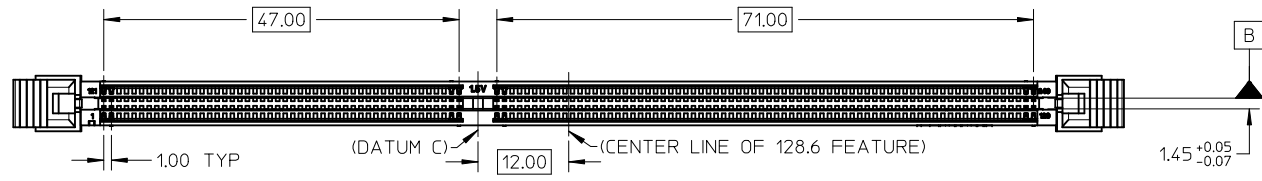
Duration at Max. Process Temperature (seconds)	5
Lead-free Process Capability	SMC & Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	2
Process Temperature max. C	260

Material Info**Reference - Drawing Numbers**

Product Specification	PS-78079-002
Sales Drawing	SD-78079-001

This document was generated on 04/16/2010

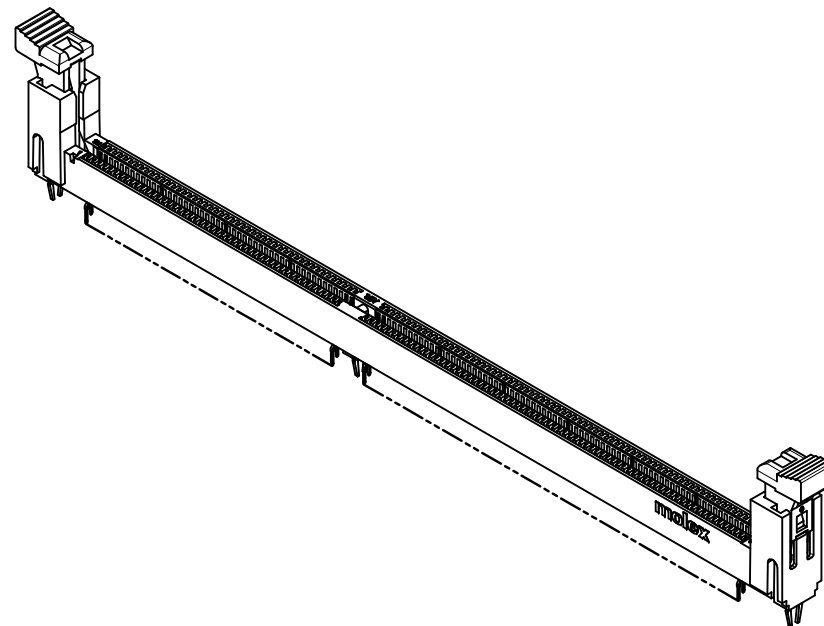
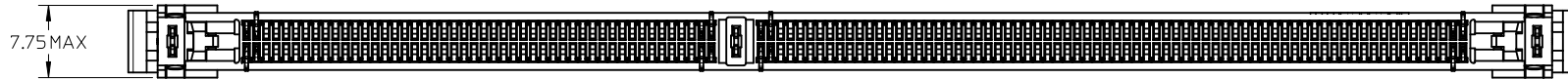
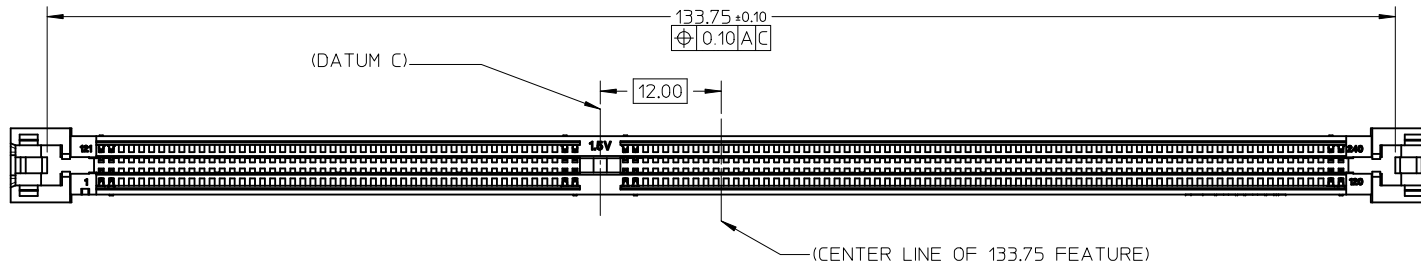
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- NOTES :
- MATERIAL : HOUSING - HIGH TEMP. NYLON, GLASS FILLED, UL 94V-0
COLOUR : SEE SHEET 6 AND 7
LATCH - HIGH TEMP NYLON, GLASS FILLED, UL 94V-0
COLOUR : SEE SHEET 6 AND 7
TERMINAL : COPPER ALLOY.
 - TERMINAL PLATING OPTIONS: SEE TABLE ON SHEETS 6 & 7.
 - PRODUCT SPECIFICATION: SEE TABLE ON SHEETS 6 & 7.
 - PACKAGING INFORMATION: PRODUCT SHALL BE PACKED IN TRAY
 - CARD SLOT ACCEPTS 1.27±0.10MM MODULE THICKNESS (MEASURED FROM P.C. PADS).
 - MOLEX LOGO, DATE & PART NO. INDICATED ON HOUSING.
 - MODULE SEATING PLANE FROM TOP OF PCB.
 - KEEP OUT ZONE RESERVED FOR LATCH.

FORKLOCK UPDATED EC NO: S2010-0888 DRWN: JAKEEWEW 2010/04/29 CHKD: CCTEH 2010/06/10 APPR: SHLENI 2010/06/13	QUALITY SYMBOLS $F_A=0$ $F_C=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± ---	mm INCH	DRAWN BY YTYANG01	DATE 2006/08/11	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL T/H			
		ANGULAR ± 1 °		CHECKED BY SHLENI	DATE 2006/09/07	MOLEX INCORPORATED			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY SHLENI	DATE 2010/06/10	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-78079-001	SHEET NO. 1 OF 8	
A4		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

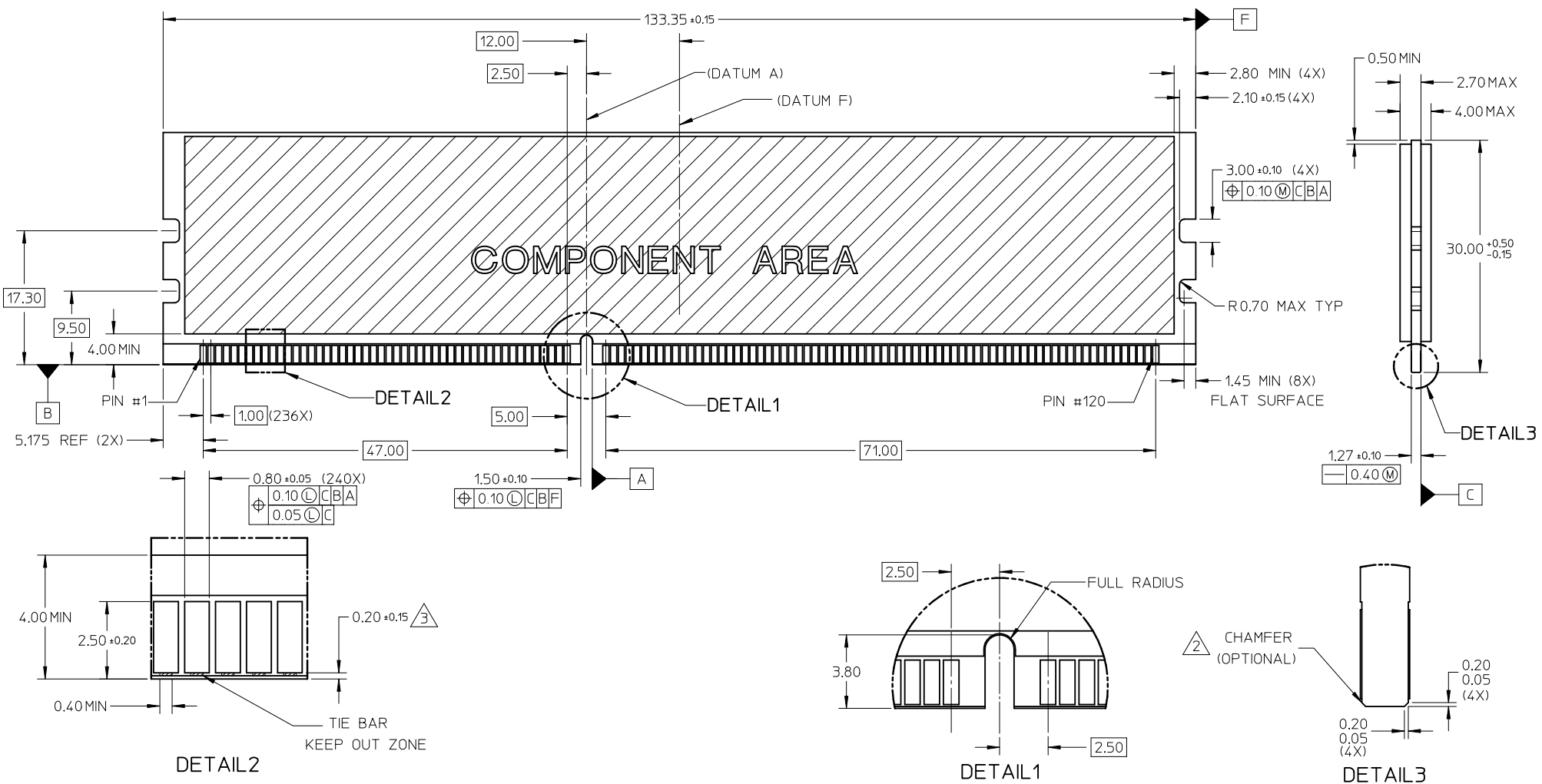
10 9 8 7 6 5 4 3 2 1



FORKLOCK UPDATED EC NO: S2010-0888 DRWN: JAKEEWEW 2010/04/29 CHKD: CCTEH 2010/06/10 APPR: SHLENI 2010/06/13	REV DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		$\nabla_A = 0$ $\nabla_C = 0$ $\nabla_P = 0$	mm	INCH	DRAWN BY YTYANG01	DATE 2006/08/11	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL T/H				
			4 PLACES	± ---	± ---	CHECKED BY SHLENI	DATE 2006/09/07	APPROVED BY SHLENI 2010/06/10			
			3 PLACES	± ---	± ---	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-78079-001		SHEET NO. 2 OF 8	
A4			2 PLACES	± 0.2	± ---	MOLEX INCORPORATED					
			1 PLACE	± ---	± ---	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			ANGULAR ± 1 °								

9 8 7 6 5 4 3 2 1

MODULE CARD
 DDR3 DUAL IN-LINE MEMORY MODULE FAMILY 1.00MM CONTACT CENTERS
 (JEDEC MO-269, ISSUE B, MAY 06)

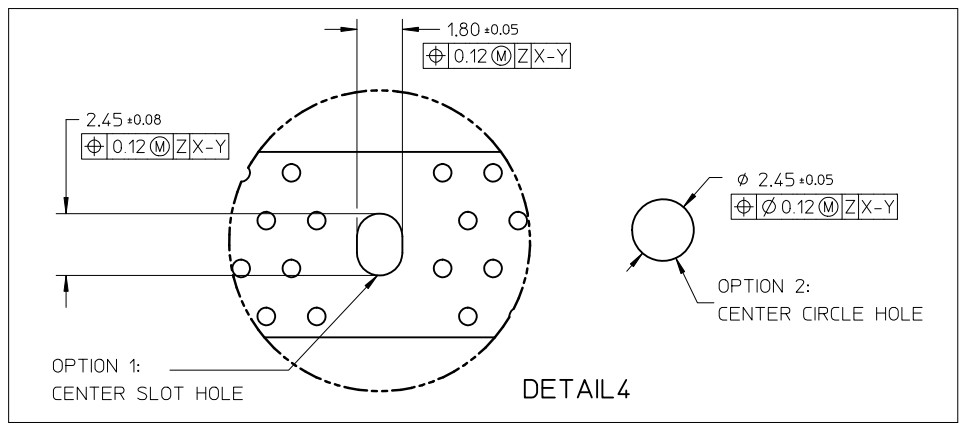
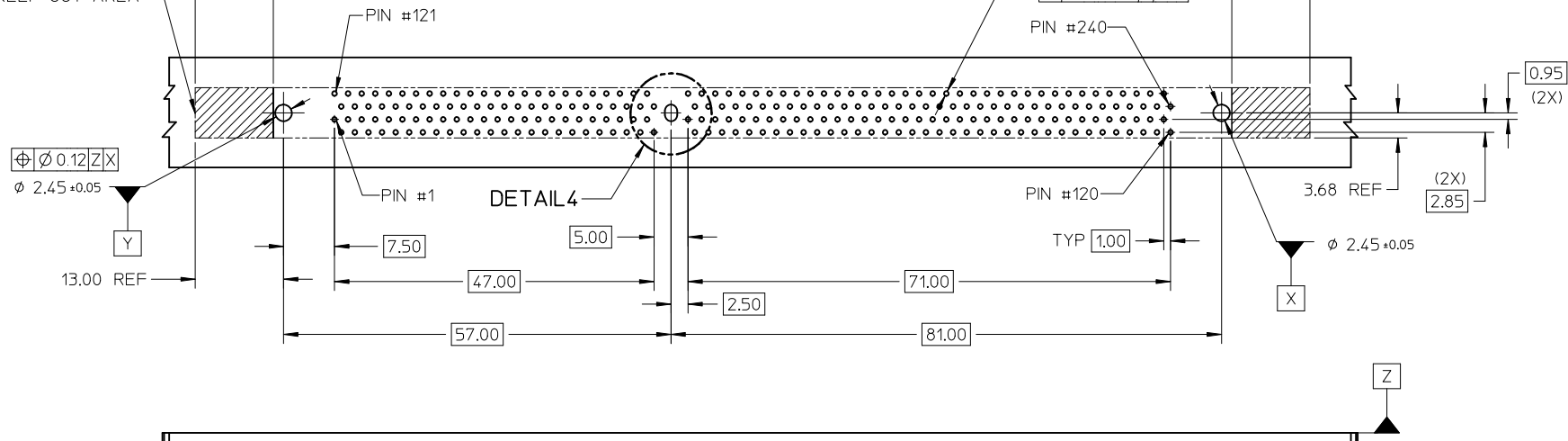


- NOTES:
- RECOMMENDED PLATING FOR CONTACT PADS:
 PREFERRED: 0.76 MICROMETERS GOLD PLATING MIN OVER 2.00 MICROMETERS NICKEL
 ALTERNATIVE: 0.05-0.75 MICROMETERS GOLD PLATING OVER 2.00 MICROMETERS NICKEL MUST USE AN ELECTRONIC CONTACT GRADE CORROSIVE BARRIER LUBRICANT
 - CHAMFER IS OPTIONAL AND IS NOT TO HIT THE GOLD PADS
 - LEADING EDGE OF GOLD PADS SPECIFIED BY KEEPOUT ZONE SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS.

FORKLOCK UPDATED EC NO: S2010-0888 DRWN: JAKEEWEW 2010/04/29 CHYK: CCTEH 2010/06/10 APPR: SHLENI 2010/06/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION										
	$F_A=0$ $F_C=0$ $F_B=0$	<table border="1"> <tr><th>mm</th><th>INCH</th></tr> <tr><td>4 PLACES</td><td>± ---</td></tr> <tr><td>3 PLACES</td><td>± ---</td></tr> <tr><td>2 PLACES</td><td>± 0.2</td></tr> <tr><td>1 PLACE</td><td>± ---</td></tr> </table>	mm	INCH	4 PLACES	± ---	3 PLACES	± ---	2 PLACES	± 0.2	1 PLACE	± ---	MM ONLY	NTS	METRIC	
	mm	INCH														
	4 PLACES	± ---														
3 PLACES	± ---															
2 PLACES	± 0.2															
1 PLACE	± ---															
<table border="1"> <tr><th>mm</th><th>INCH</th></tr> <tr><td colspan="2">ANGULAR ± 1 °</td></tr> </table>	mm	INCH	ANGULAR ± 1 °		DRAWN BY: YTYANG01 CHECKED BY: SHLENI APPROVED BY: SHLENI MATERIAL NO.	DATE: 2006/08/11 DATE: 2006/09/07 DATE: 2010/06/10	TITLE		TITLE: DDR3 DIMM, 1.00MM PITCH 240 CKTS, VERTICAL T/H MOLEX INCORPORATED							
mm	INCH															
ANGULAR ± 1 °																
A4	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	DOCUMENT NO.	SHEET NO.	SD-78079-001 3 OF 8											

10 9 8 7 6 5 4 3 2 1

KEEP OUT AREA

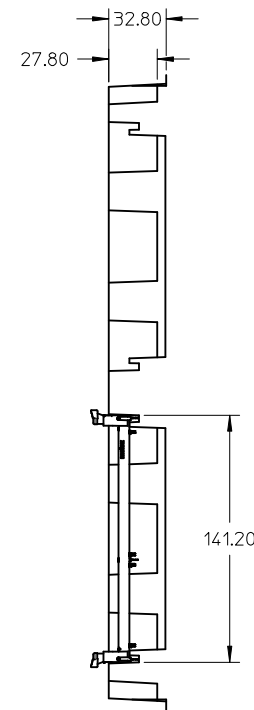
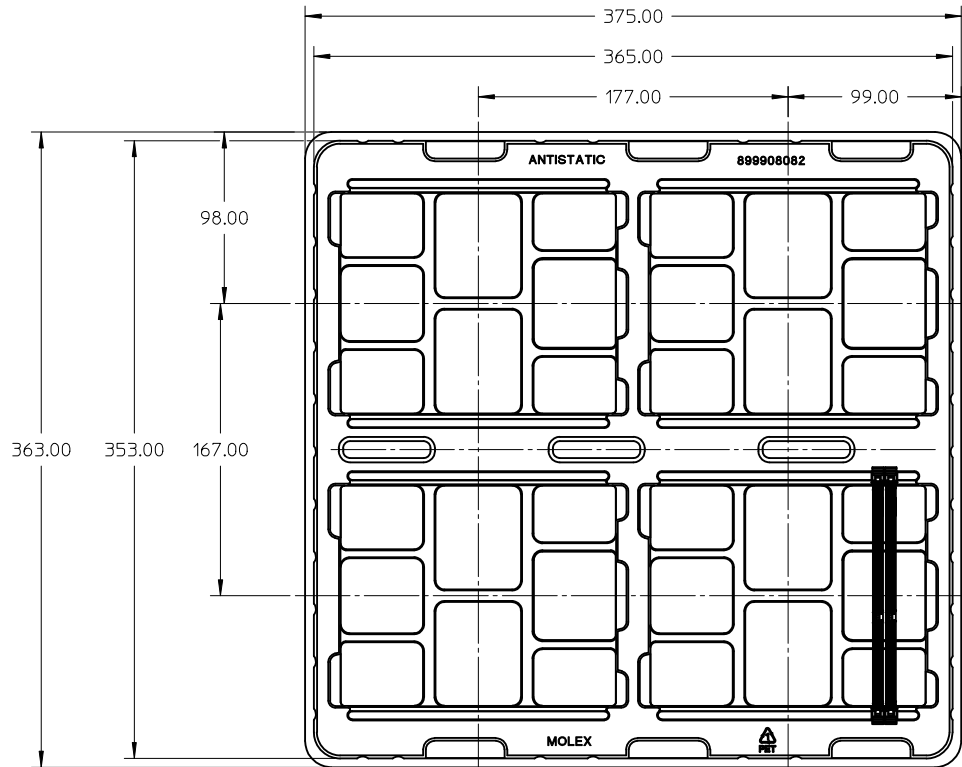


NOTE:
 1. KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR (INCLUDING LATCH) IS MOUNTED ON THE PCB.

FORKLOCK UPDATED EC NO: S2010-0888 DRWN: JAKEEWEW 2010/04/29 CHKD: CCTEH 2010/06/10 APPR: SHLENI 2010/06/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	$F_A=0$	mm	INCH	DRAWN BY	DATE	TITLE			
	$F_C=0$	4 PLACES ± ---	± ---	YTYANG01	2006/08/11	DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL T/H			
	$F_P=0$	3 PLACES ± ---	± ---	CHECKED BY	DATE	MATERIAL NO. DOCUMENT NO.			
	2 PLACES ± 0.2	± ---	SHLENI	2006/09/07	SHEET NO.				
	1 PLACE ± ---	± ---	APPROVED BY	DATE	MATERIAL NO. DOCUMENT NO.				
	ANGULAR ± 1 °		SHLENI	2010/06/10	SHEET NO.				
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-78079-001				
A4	REV	SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1



NOTES:
1. QTY OF CAVITY: 20 X 4 = 80 PCS

FORKLOCK UPDATED EC NO: S2010-0888 DRWN: JAKEEWEW 2010/04/29 CHKD: CCTEH 2010/06/10 APPR: SHLENI 2010/06/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	$F_A=0$	4 PLACES	mm	INCH	DRAWN BY YTYANG01	DATE 2006/08/11	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL T/H		
	$F_C=0$	3 PLACES	± ---	± ---	CHECKED BY SHLENI	DATE 2006/09/07	MATERIAL NO. SEE TABLE		
	$F_P=0$	2 PLACES	± 0.2	± ---	APPROVED BY SHLENI	DATE 2010/06/10	DOCUMENT NO. SD-78079-001		
		1 PLACE	± ---	± ---	ANGULAR ± 1 °		SHEET NO. 5 OF 8		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

9 8 7 6 5 4 3 2 1

ASSEMBLY PART NO.	VOLTAGE KEY	HOUSING COLOR	LATCH COLOR	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	PRODUCT SPECIFICATION		
78079-0001	CENTRE (1.5V)	BLACK	BLACK	2.67	1.57	0.38 MICROMETER/ 15 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-001		
78079-0003				3.00	2.18				
78079-0002				3.18	2.36				
78079-0011				2.67	1.57	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE		PS-78079-002	
78079-0013				3.00	2.18				
78079-0012				3.18	2.36				
78079-0021				2.67	1.57	0.076 MICROMETER/ 3 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE		PS-78079-003	
78079-0023				3.00	2.18				
78079-0022				3.18	2.36				
78079-0051			NATURAL (OFFWHITE)		0.38 MICROMETER/ 15 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-001			
78079-0053							2.67	1.57	
78079-0052							3.00	2.18	
78079-0061					3.18		2.36	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-002
78079-0063					2.67		1.57		
78079-0062					3.00		2.18		
78079-0071					3.18		2.36	0.076 MICROMETER/ 3 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-003
78079-0073					2.67		1.57		
78079-0072					3.00		2.18		

FORKLOCK UPDATED EC NO: S2010-0888 DRWN: JAKEEWEW 2010/04/29 CHKD: CCTEH 2010/06/10 APPR: SHLENI 2010/06/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	$F_A=0$ $F_C=0$ $F_P=0$	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± ---	DRAWN BY: YTYANG01 DATE: 2006/08/11 CHECKED BY: SHLENI DATE: 2006/09/07 APPROVED BY: SHLENI DATE: 2010/06/10	TITLE: DDR3 DIMM, 1.00MM PITCH 240 CKTS, VERTICAL T/H			
		ANGULAR ± 1 °	MATERIAL NO. DOCUMENT NO. SHEET NO. SEE TABLE SD-78079-001 6 OF 8				
	A4	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE: A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

ASSEMBLY PART NO.	VOLTAGE KEY	HOUSING COLOR	LATCH COLOR	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	PRODUCT SPECIFICATION	
78079-0201	CENTRE (1.5V)	BLUE	NATURAL (OFFWHITE)	2.67	1.57	0.38 MICROMETER/ 15 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-001	
78079-0203				3.00	2.18			
78079-0202				3.18	2.36			
78079-0211				2.67	1.57	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE		PS-78079-002
78079-0213				3.00	2.18			
78079-0212				3.18	2.36			
78079-0221		2.67	1.57	0.076 MICROMETER/ 3 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-003			
78079-0223		3.00	2.18					
78079-0222		3.18	2.36					
78079-0351		GREEN	NATURAL (OFFWHITE)	2.67		1.57	0.38 MICROMETER/ 15 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-001
78079-0353				3.00		2.18		
78079-0352				3.18		2.36		
78079-0361				2.67	1.57	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-002	
78079-0363				3.00	2.18			
78079-0362				3.18	2.36			
78079-0371				2.67	1.57	0.076 MICROMETER/ 3 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE		PS-78079-003
78079-0373				3.00	2.18			
78079-0372		3.18	2.36					

FORKLOCK UPDATED EC NO: S2010-0888 DRWN: JAKEEWEW 2010/04/29 CHKD: CCTEH 2010/06/10 APPR: SHLENI 2010/06/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	$F_A=0$ $F_C=0$ $F_P=0$	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1 °	DRAWN BY: YTYANG01 DATE: 2006/08/11 CHECKED BY: SHLENI DATE: 2006/09/07 APPROVED BY: SHLENI DATE: 2010/06/10	TITLE: DDR3 DIMM, 1.00MM PITCH 240 CKTS, VERTICAL T/H			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. DOCUMENT NO. SEE TABLE SD-78079-001	SHEET NO. 7 OF 8			
	A4		SIZE: A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

F

E


D

C

B

A

ASSEMBLY PART NO.	VOLTAGE KEY	HOUSING COLOR	LATCH COLOR	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	PRODUCT SPECIFICATION			
78079-0101	CENTRE (1.5V)	NATURAL (OFFWHITE)	NATURAL (OFFWHITE)	2.67	1.57	0.38 MICROMETER/ 15 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDERTAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-001			
78079-0103				3.00	2.18					
78079-0102				3.18	2.36					
78079-0111							2.67	1.57	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDERTAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-002
78079-0113							3.00	2.18		
78079-0112							3.18	2.36		
78079-0121							2.67	1.57	0.076 MICROMETER/ 3 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDERTAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-003
78079-0123							3.00	2.18		
78079-0122				3.18	2.36					

FORKLOCK UPDATED EC NO: S2010-0888 DRWN: JAKEEWEW 2010/04/29 CHKD: CTEH 2010/06/10 APPR: SHLENI 2010/06/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	$\nabla_A = 0$	4 PLACES	mm INCH	DRAWN BY YTYANG01	DATE 2006/08/11	TITLE DDR3 DIMM, 1.00MM PITCH 240 CKTS, VERTICAL T/H
	$\nabla_C = 0$	3 PLACES	\pm --- \pm ---	CHECKED BY SHLENI	DATE 2006/09/07	 MOLEX INCORPORATED
	$\nabla_P = 0$	2 PLACES	\pm 0.2 \pm ---	APPROVED BY SHLENI	DATE 2010/06/10	
	1 PLACE	\pm --- \pm ---	ANGULAR \pm 1 °		MATERIAL NO.	DOCUMENT NO.
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE	SD-78079-001
			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		